



SB520/SB530/SB550 SCHOTTKY RECTIFIER

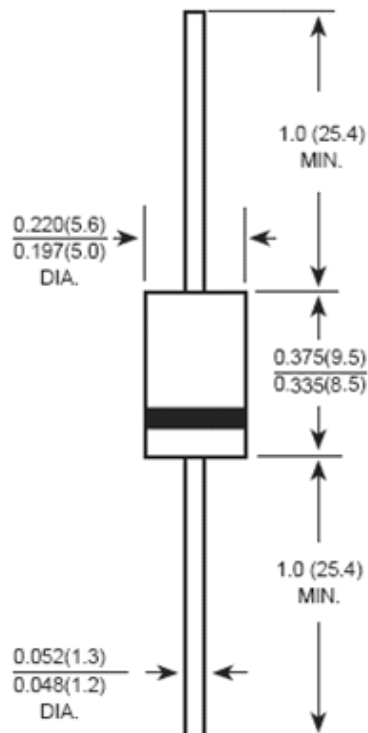
Applications:

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection
- Disk drives
- Battery charging

Features:

- Schottky Barrier Chip
- Guard Ring Die Construction for Transient Protection
- High Current Capability
- Low Power Loss, High Efficiency
- High Surge Current Capability
- For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Applications
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

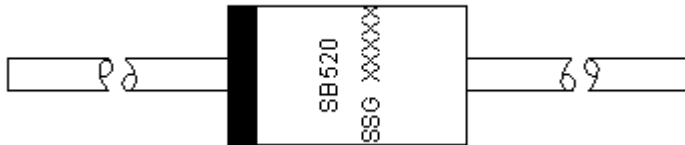
Mechanical Dimensions: In Inches / mm



DO-201AD



Marking Diagram:



Where XXXXX is YYWWL

- SB = Device Type
- 5 = Forward Current (5A)
- 20 = Reverse Voltage (20V)
- SSG = SSG
- YY = Year
- WW = Week
- L = Lot Number

Cautions : Molding resin
Epoxy resin UL:94V-0

Ordering Information:

| Device | Package | Shipping |
|-------------|-----------------------|-----------------|
| SB520-SB550 | DO-201AD (Pb-Free) | 1250 pcs / Tape |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification.



Maximum Ratings and Electrical Characteristics @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Single Phase, half wave, 60Hz, resistive or inductive load.
For capacitive load, derate current by 20%.

| Characteristic | Symbol | SB520 | SB530 | SB550 | Unit |
|---|---------------------------------|-------------|-------|-------|--------------------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V_{RRM} V_{RWM} V_R | 20 | 30 | 50 | V |
| Average Rectified Output Current (Note 1) @ $T_L = 100^{\circ}\text{C}$ | I_o | 5.0 | | | A |
| Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method) | I_{FSM} | 120 | | | A |
| Forward Voltage @ $I_F = 5.0\text{A}$ | V_{FM} | 0.55 | 0.70 | | V |
| Peak Reverse Current At Rated DC Blocking Voltage @ $T_A = 25^{\circ}\text{C}$ @ $T_A = 100^{\circ}\text{C}$ | I_{RM} | 0.5 20 | | | mA |
| Typical Junction Capacitance (Note 2) @ $V_R = 5\text{V}$ | C_j | 550 | 400 | | pF |
| Typical Thermal Resistance Junction to Ambient (Note 1) | $R_{\theta JA}$ | 25 | | | K/W |
| Typical Thermal Resistance Junction to Lead (Note 3) | $R_{\theta JL}$ | 8 | | | K/W |
| Junction Temperature | T_J | -55 to +150 | | | $^{\circ}\text{C}$ |
| Storage Temperature Range | T_{STG} | -55 to +150 | | | $^{\circ}\text{C}$ |
| Approximate Weight | wt | 1.02 | | | g |
| Case Style | DO-201AD | | | | |

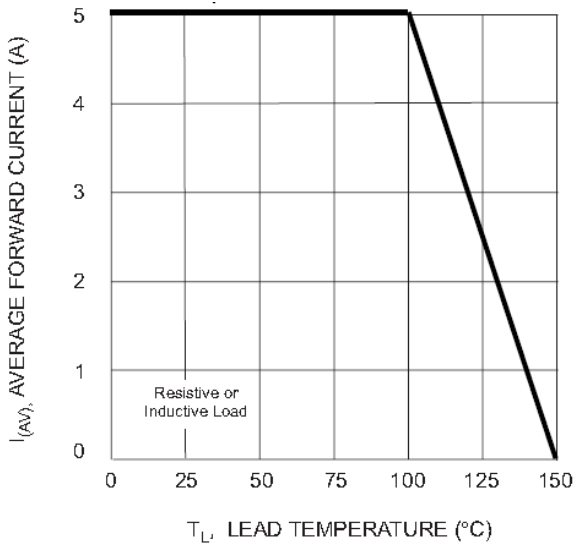
- Note:1. Valid provided that leads are kept at ambient temperature at a distance of 9.5mm from the case.
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.
3. Thermal resistance junction to lead vertical P.C.B. mounted, 0.375" (9.5mm) lead length.



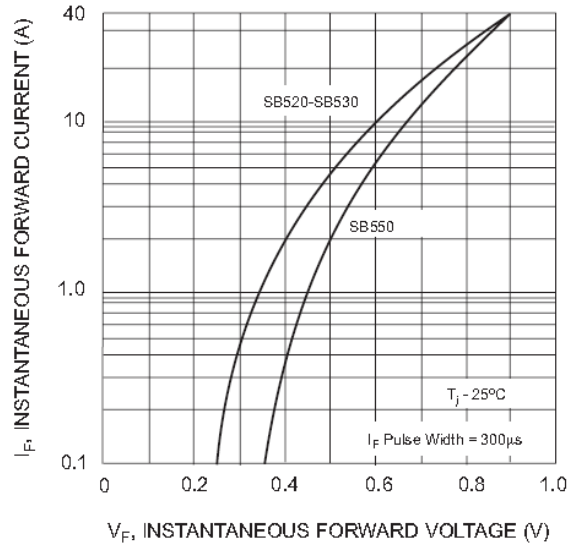
Technical Data

Green Products

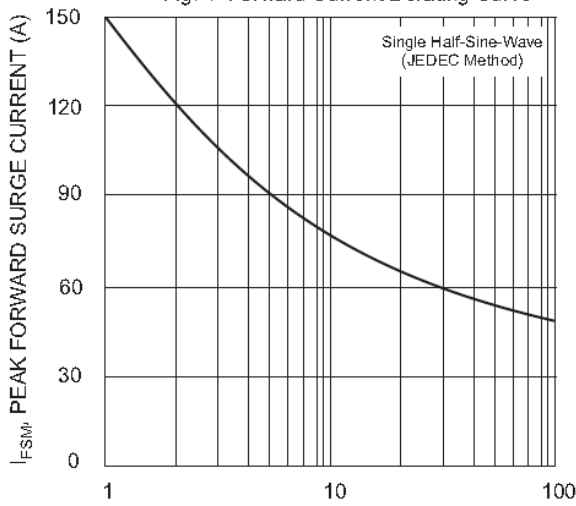
Data Sheet N1708, Rev. -



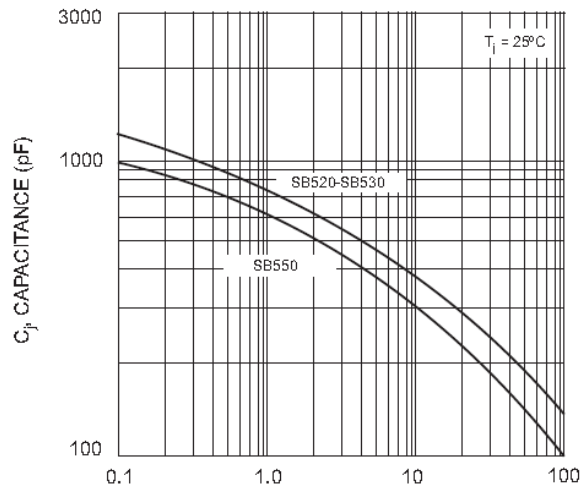
T_L , LEAD TEMPERATURE (°C)
Fig. 1 Forward Current Derating Curve



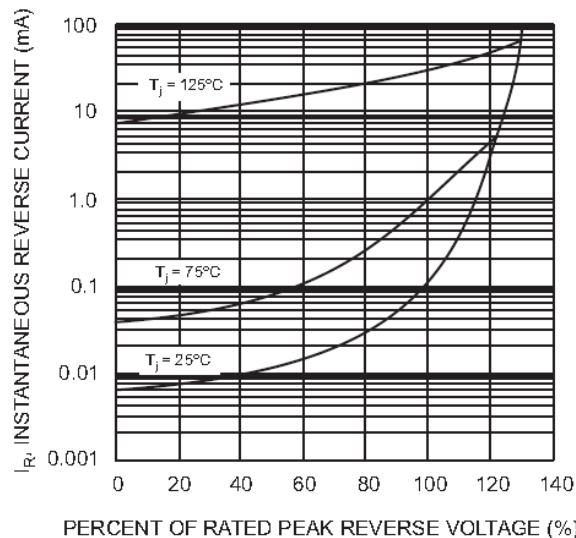
V_F , INSTANTANEOUS FORWARD VOLTAGE (V)
Fig. 2 Typical Forward Characteristics



NUMBER OF CYCLES AT 60Hz
Fig. 3 Max Non-Repetitive Peak Fwd Surge Current



V_R , REVERSE VOLTAGE (V)
Fig. 4 Typical Junction Capacitance



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)
Fig. 5 Typical Reverse Characteristics



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